## 09-30-1999

HEET

U.S. DEPARTMENT OF COMMERCE Patent and Trademark O.

Docket No.: S-2455

OMB No. 1651-10 <u>101</u>158587

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1. Name of conveying party(ies):    Akira OKADA    Satoko YAMASHITA    Koji SHIMIZU  Additional name(c: & addresses attached? □ Yes ☑ No  3. Nature of Conveyance:    ☑ Assignment □ Merger    □ Security Agreement □ Change of Name    □ Other	2. Name and address of receiving party(ies)  Name: KYOWA CHEMICAL INDUSTRY CO., LTD.  Internal Address:  Street Address: 305, Yashimanishi-machi Takamatsu-shi City: Kagawa-ken State: Japan  ZIP:  Additional name(s) & addresses attached? • Yes No
Execution Date <u>September 10, 1999</u> 4. Application number(s) or patent number(s):	00/000/120
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**PATENT REEL: 010267 FRAME: 0209** 

09/28/1999 KHARL 03 FC:561

## ASSIGNMENT

WHEREAS, We, Akira OKADA, Satoko YAMASHITA and Koji SHIMIZU, all citizens of Japan,

residing at Takamatsu-shi, Kagawa-ken, Japan, Kotohira-cho, Nakatado-gun, Kagawa-ken, Japan and Sakaide-shi, Kagawa-ken, Japan, respectively

, (hereafter referred to as Inventors), have invented certain new and useful improvements in HYDROTALCITE COMPOUNDS OF LOW URANIUM (U) CONTENT AND PROCESSES FOR THEIR PREPARATION for which an application for United States Letters Patent was signed by us on even date herewith; and

WHEREAS, KYOWA CHEMICAL INDUSTRY CO., LTD.
a corporation of Japan , having a place of business at
305, Yashimanishi-machi, Takamatsu-shi, Kagawa-ken, Japan
(hereafter referred to as Company), is desirous of acquiring the entire right,
title and interest in and to said invention and in and to any Letters Patent
that may be granted therefor in the United States and in any and all foreign
countries.

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

Signed in the presence of:

Signed: Akiva Okada
Signed Satoho Yamashita
Signed: Kgi Shimizu
Signed:
Signed: PATENT
Signed: REEL: 010267 FRAME: 0210